Introduction of Hot Melt Adhesive Film for Hot Melt Pressure Sensitive Adhesive Block Packaging

Detail Introduction :

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Hot-melt pressure-sensitive adhesive is a kind of adhesive product used a lot now. Unlike hot-melt adhesive, it has a specific initial viscosity, which can produce initial adhesion to the adherend under the action of pressure. Catch. Because of this, the storage of raw materials for pressure-sensitive adhesives is a complex problem in producing pressure-sensitive adhesives.

Due to its initial viscosity, the pressure-sensitive adhesive blocks cannot be directly stacked together. They must be wrapped with non-sticky plastic film. The film is torn apart before production and put into the furnace, which greatly reduces production efficiency. To solve this problem, people have thought of a method of packaging hot-melt pressure-sensitive adhesive with hot-melt adhesive film.

What is the principle of encapsulated hot melt adhesive film?

We know that hot-melt adhesive film is different from the hot-melt pressure-sensitive adhesive. It does not have initial viscosity at room temperature, so after the hot-melt pressure-sensitive adhesive block is packaged, there is no bonding problem before the adhesive block. On the other hand, the properties of the hot-melt adhesive film itself are similar to that of the hot-melt pressure-sensitive adhesive, and the compatibility has reached a more rational state, so it is not necessary to tear off the hot-melt adhesive film and then put the glue block into the furnace before production. The hot melt adhesive film can be put together with the glue block, and the performance of the produced glue will not be greatly affected.

What are the characteristics of the encapsulated hot melt adhesive film?

The encapsulated hot melt adhesive film generally has the characteristics of low melting point, good fluidity, good compatibility and low cost. The low melting point is because the melting point of the hot-melt pressure-sensitive adhesive itself is relatively low. If the melting point of the encapsulated hot-melt adhesive film is too high, it will be difficult to melt, and the melting point of the produced hot-melt pressure-sensitive adhesive will also be produced. Influence. Generally, the melting point of the encapsulated hot melt adhesive film is 60-80 °C. The fluidity of the adhesive film is good, and the packaged hot melt adhesive block is thrown into the furnace; and it can be melted off well without leaving residue during the melting process, and it will not cause the blockage of the machine.

It is also a reason to require good compatibility. After the hot melt adhesive film is melted, it can be well fused with the hot melt pressure-sensitive adhesive without affecting the performance of the hot-melt pressure-sensitive adhesive. The low cost is also easy to understand because the overmolded hot melt adhesive film essentially isolates the hot-melt pressure-sensitive adhesive block, making it easy to store and handle, so the thickness requirements must not be high, generally, That is, the thickness of 2 wires can meet the requirements, so the manufacturing cost is relatively low.

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